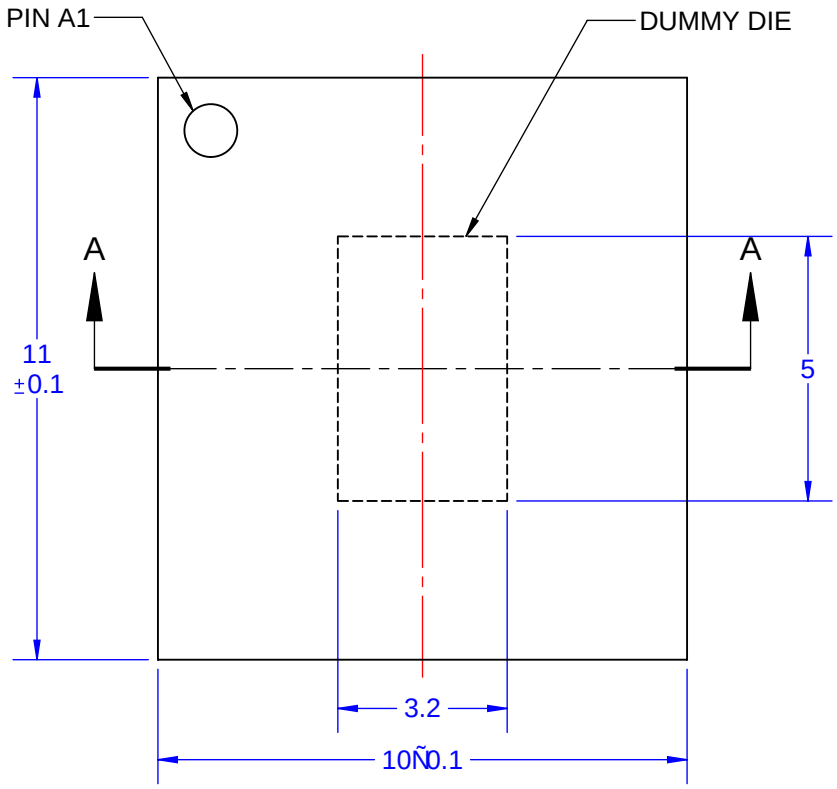
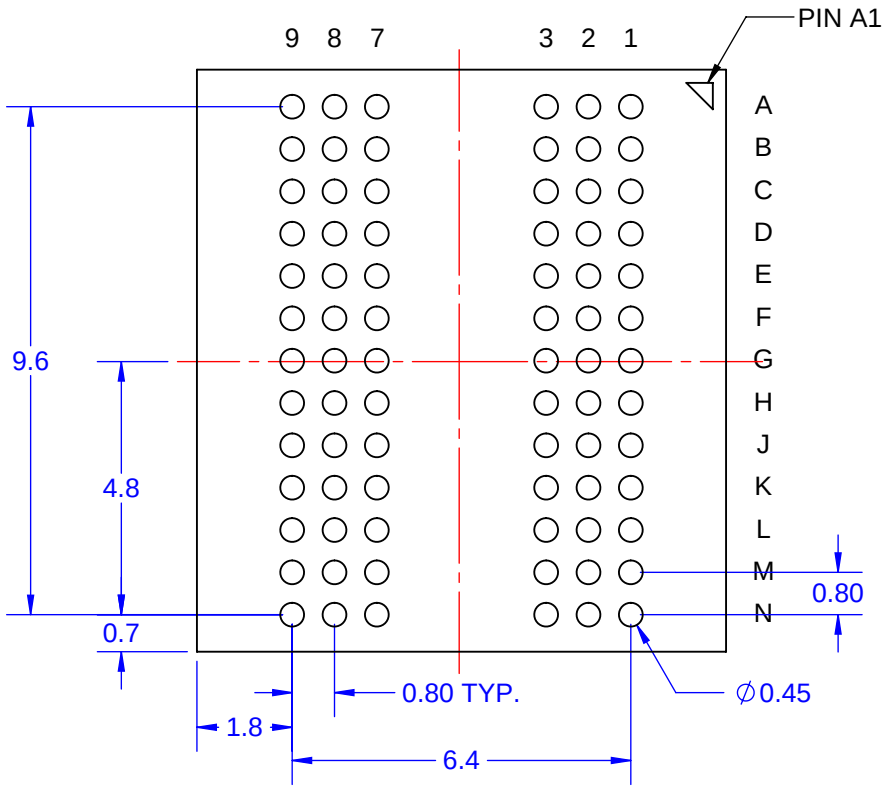
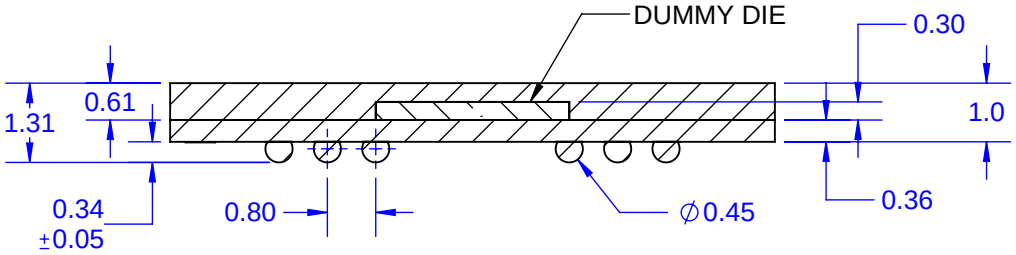
TOP VIEW



BALL VIEW





SECTION A-A
SCALE 8 : 1

Notes: Unless Otherwise Specified).

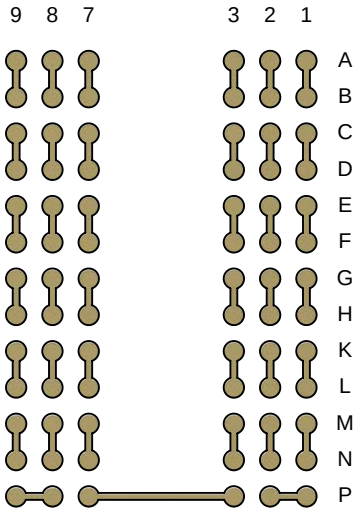
1) ALL DIMENSIONS ARE IN MM.
2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
3) BALL DIAMETER (BEFORE REFLOW): 0.50mm.
4) SOLDER MASK DEFINED PAD OPENING: 0.42mm (16.5 MIL).
5) PAD Cu DIAMETER: 0.50mm (19.7 MIL).
6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
7) DUMMY DIE IS OPTIONAL.
8) DAISY CHAIN PATTERN (SEE PAGE 2).
9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

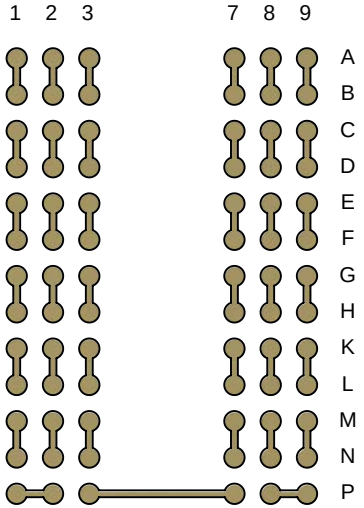
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA78T.8C-DC635D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA78T.8-DC635D	Sn63/Pb37	Sn63	NO	YES

APPROVALS		DATE	TopLine®			
DRAWN	T.Au	6/11/2021				
ENG	M. Hart	6/11/2021	TITLE	BGA78T.8-DC635D DAISY CHAIN		
MFG						
QA			SCALE	SIZE	DRAWING NO.	REV
CUST			7:1	A	586353	A
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 3	

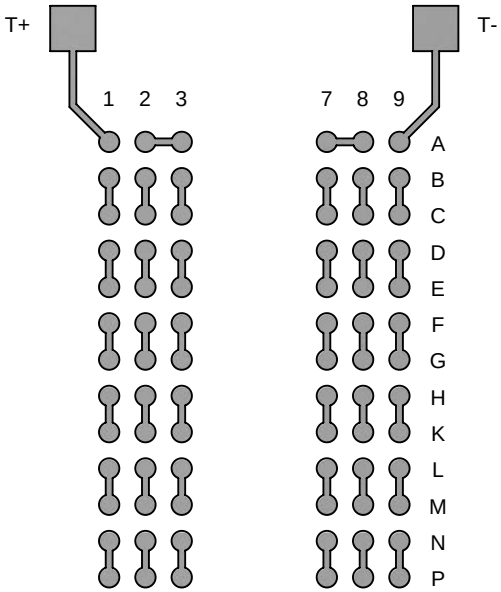
BALL VIEW



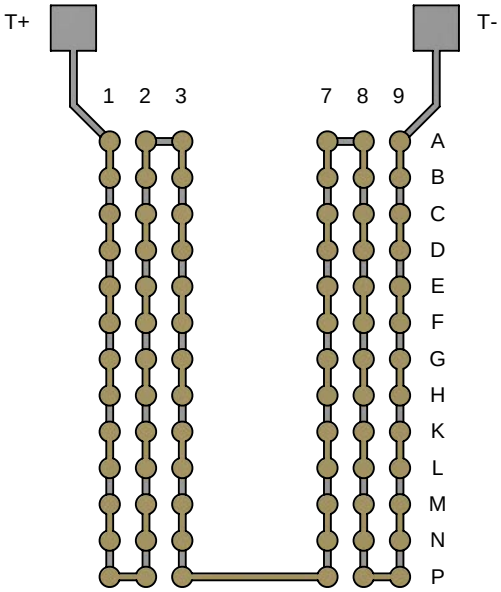
BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING



Notes:

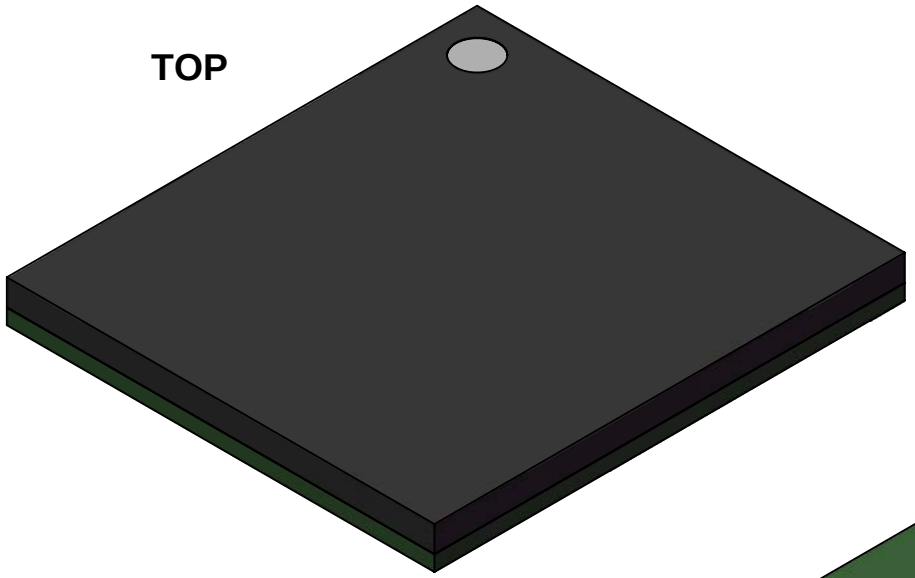
1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
   DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2) PCB Cu BALL PAD DIAMETER: 0.5mm (19.7 MIL).
3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.42mm (16.5 MIL).

TopLine®

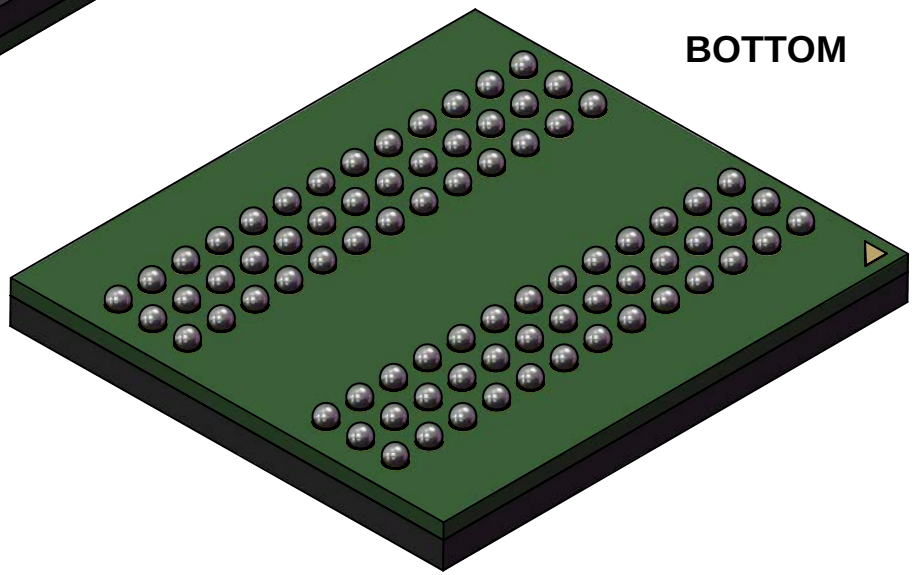
TITLE	BGA78T.8-DC635D DAISY CHAIN		
SCALE	SIZE	DRAWING NO.	REV
6:1	A	586353	A
DO NOT SCALE DRAWING		SHEET 2 OF 3	

MODEL

TOP



BOTTOM



TopLine®			
TITLE: BGA78T.8-DC635D DAISY CHAIN			
SCALE: 8:1	SIZE: A	DRAWING NO.: 586353	REV: A
DO NOT SCALE DRAWING		SHEET 3 OF 3	